

### MAMX-011037-DIE

Rev. V3

#### Features

- Low Conversion Loss: 6.5 dB
- High Linearity: 20 dBm IIP3
- Wide IF Bandwidth: DC to 20 GHz
- High Isolation
- Die Size: 1.15 × 0.97 × 0.10 mm
- RoHS\* Compliant

### **Applications**

- Test & Measurement
- Microwave Radio
- Radar

#### Description

MAMX-011037-DIE is a double-balanced passive diode mixer MMIC. The mixer offers low conversion loss, high linearity and a wide IF bandwidth. The double-balanced circuit configuration provides excellent port isolation while internal 50  $\Omega$  matching simplifies its application.

MAMX-011037-DIE is also available in a 3 mm QFN package. Refer to datasheet MAMX-011054.

### **Functional Schematic**



### Bond-pad Configuration

Pad #	Function
1,3,4,6,7,9,10	GND <sup>2</sup>
2	LO
5	IF
8	RF

2. These pads are internally connected to ground, and they can be left unconnected.

3. The backside of the die must be connected to RF, DC and thermal ground.

#### **Ordering Information**

Part Number	Package		
MAMX-011037-DIE	Vacuum Release Gel Pack <sup>1</sup>		
MAMX-011037-SB2	Sample Board		

1. Die quantity varies.

\* Restrictions on Hazardous Substances, compliant to current RoHS EU directive.

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# Electrical Specifications<sup>4</sup>: $F_{IF}$ = 1 GHz, $P_{LO}$ = +15 dBm, $T_A$ = 25°C, $Z_0$ = 50 $\Omega$

Parameter	Test Conditions	Units	Min.	Тур.	Max.
LO and RF Frequency	_	GHz	18	_	46
IF Frequency	_	GHz	0	_	20
LO Power	_	dBm		15	_
Conversion Loss	18 - 24 GHz 24 - 40 GHz 40 - 46 GHz		_	6.5 6.5 6.5	12 10 11
Input P1dB	_	dBm	_	12	—
Input IP3	$P_{RF}$ = -10 dBm/tone, $\Delta f$ = 1 MHz	dBm	—	20	—
Input IP2	$P_{RF}$ = -10 dBm/tone, $\Delta f$ = 1 MHz	dBm	—	50	—
LO-to-RF Isolation	_	dB	_	35	—
LO-to-IF Isolation	18 - 24 GHz 24 - 40 GHz 40 - 46 GHz	dB	25 27 23	37 45 44	_
RF-to-IF Isolation	18 - 24 GHz 24 - 40 GHz 40 - 46 GHz	dB		10 24 27	_
RF Return Loss	RF = 40 GHz	dB	_	5	—
IF Return Loss	IF = 1 GHz	dB	—	15	—

4. All specifications refer to down-conversion operation, unless otherwise noted.

### Absolute Maximum Ratings<sup>5,6</sup>

Parameter	Absolute Maximum		
LO Power	23 dBm		
RF or IF Power	20 dBm		
Junction Temperature <sup>7</sup>	+150°C		
Operating Temperature	-55°C to +85°C		
Storage Temperature	-65°C to +150°C		

5. Exceeding any one or combination of these limits may cause permanent damage to this device.

MACOM does not recommend sustained operation near these survivability limits.

 Operating at nominal conditions with T<sub>J</sub> ≤ +150°C will ensure MTTF > 1 x 10<sup>6</sup> hours.

# Handling Procedures

Please observe the following precautions to avoid damage:

#### **Static Sensitivity**

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 1B devices.

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## Typical Performance Curves, $P_{LO}$ = +15 dBm, $T_A$ = 25°C

#### IF Bandwidth & Return Loss





**RF Return Loss** 



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Typical Performance Curves vs. LO Power, T<sub>A</sub> = 25°C

Input IP3 at P<sub>LO</sub> = +15 dBm



**Up Conversion Gain** 





Input IP2 at  $P_{LO}$  = +15 dBm



All performance curves refer to down-conversion operation, unless otherwise noted. Two-tone input power = -10 dBm each tone, 1 MHz spacing.

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# **Conversion Gain** 0 Conversion Gain (dB) -5 -10 +25°C -55°C +85°C -15 -20 16 24 32 40 48 RF Frequency (GHz) Input IP2 80 60 40 +25°C -55°C +85°C 20

### Typical Performance Curves vs. Temperature, P<sub>LO</sub> = +15 dBm

Input IP3 40 30 IIP3 (dBm) 20 +25°C - -55°C +85°C 10 0 24 48 32 40 16 RF Frequency (GHz)



All performance curves refer to down-conversion operation, unless otherwise noted. Two-tone input power = -10 dBm each tone, 1 MHz spacing.

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## MxN Spurious Rejection @ IF Port (dBc IF)

RF = 24 GHz @ -10 dBm LO = 25 GHz @ +15 dBm

	NxLO					
MxRF	0	1	2	3	4	
0	х	14	24	х	x	
1	4	0	22	х	x	
2	75	61	67	66	x	
3	х	86	66	71	75	
4	х	х	88	99	95	

### **Assembly Guideline**



#### Notes:

Attach bare die to PCB or carrier using conductive epoxy. Bond die signal pads to PCB 50  $\Omega$  traces using 1.0 mil gold wire. Two bond wires are recommended on each signal pad for optimal performance. There is no need to bond the die GND pads.

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### **Outline Drawing**



Notes:

Units are in microns with a tolerance of  $\pm 5 \ \mu$ m, except for die exterior dimensions which are street-center-to-street-center – nominal kerf,  $\pm 20 \ \mu$ m tolerance.

Die thickness is 100 ±10  $\mu$ m.

RF, LO and IF Bond-pads are 160 x 100 µm.

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